



128K x 36, 256K x 18
3.3V Synchronous SRAMs
2.5V I/O, Flow-Through Outputs
Burst Counter, Single Cycle Deselect

IDT71V2577
IDT71V2579

Features

- ♦ 128K x 36, 256K x 18 memory configurations
- ♦ Supports fast access times:
 - Commercial:
 - 7.5ns up to 117MHz clock frequency
 - Commercial and Industrial:
 - 8.0ns up to 100MHz clock frequency
 - 8.5ns up to 87MHz clock frequency
- ♦ $\overline{\text{LBO}}$ input selects interleaved or linear burst mode
- ♦ Self-timed write cycle with global write control ($\overline{\text{GW}}$), byte write enable ($\overline{\text{BWE}}$), and byte writes ($\overline{\text{BWx}}$)
- ♦ 3.3V core power supply
- ♦ Power down controlled by ZZ input
- ♦ 2.5V I/O
- ♦ Packaged in a JEDEC Standard 100-pin plastic thin quad flatpack (TQFP), 119 ball grid array (BGA) and 165 fine pitch ball grid array (fBGA)

Description

The IDT71V2577/79 are high-speed SRAMs organized as 128K x 36/256K x 18. The IDT71V2577/79 SRAMs contain write, data, address and control registers. There are no registers in the data output path (flow-through architecture). Internal logic allows the SRAM to generate a self-timed write based upon a decision which can be left until the end of the write cycle.

The burst mode feature offers the highest level of performance to the system designer, as the IDT71V2577/79 can provide four cycles of data for a single address presented to the SRAM. An internal burst address counter accepts the first cycle address from the processor, initiating the access sequence. The first cycle of output data will flow-through from the array after a clock-to-data access time delay from the rising clock edge of the same cycle. If burst mode operation is selected ($\overline{\text{ADV}}=\text{LOW}$), the subsequent three cycles of output data will be available to the user on the next three rising clock edges. The order of these three addresses are defined by the internal burst counter and the $\overline{\text{LBO}}$ input pin.

The IDT71V2577/79 SRAMs utilize IDT's latest high-performance CMOS process and are packaged in a JEDEC standard 14mm x 20mm 100-pin thin plastic quad flatpack (TQFP) as well as a 119 ball grid array (BGA) and a 165 fine pitch ball grid array (fBGA).

Pin Description Summary

A0-A17	Address Inputs	Input	Synchronous
$\overline{\text{CE}}$	Chip Enable	Input	Synchronous
CS0, $\overline{\text{CS}}_1$	Chip Selects	Input	Synchronous
$\overline{\text{OE}}$	Output Enable	Input	Asynchronous
$\overline{\text{GW}}$	Global Write Enable	Input	Synchronous
$\overline{\text{BWE}}$	Byte Write Enable	Input	Synchronous
$\overline{\text{BW}}_1$, $\overline{\text{BW}}_2$, $\overline{\text{BW}}_3$, $\overline{\text{BW}}_4^{(1)}$	Individual Byte Write Selects	Input	Synchronous
CLK	Clock	Input	N/A
$\overline{\text{ADV}}$	Burst Address Advance	Input	Synchronous
$\overline{\text{ADSC}}$	Address Status (Cache Controller)	Input	Synchronous
$\overline{\text{ADSP}}$	Address Status (Processor)	Input	Synchronous
$\overline{\text{LBO}}$	Linear / Interleaved Burst Order	Input	DC
ZZ	Sleep Mode	Input	Asynchronous
I/O0-I/O31, I/OP1-I/OP4	Data Input / Output	I/O	Synchronous
VDD, VDDQ	Core Power, I/O Power	Supply	N/A
VSS	Ground	Supply	N/A

4877 tbl 01

NOTE:

1. $\overline{\text{BW}}_3$ and $\overline{\text{BW}}_4$ are not applicable for the IDT71V2579.

OCTOBER 2000

Pin Definition⁽¹⁾

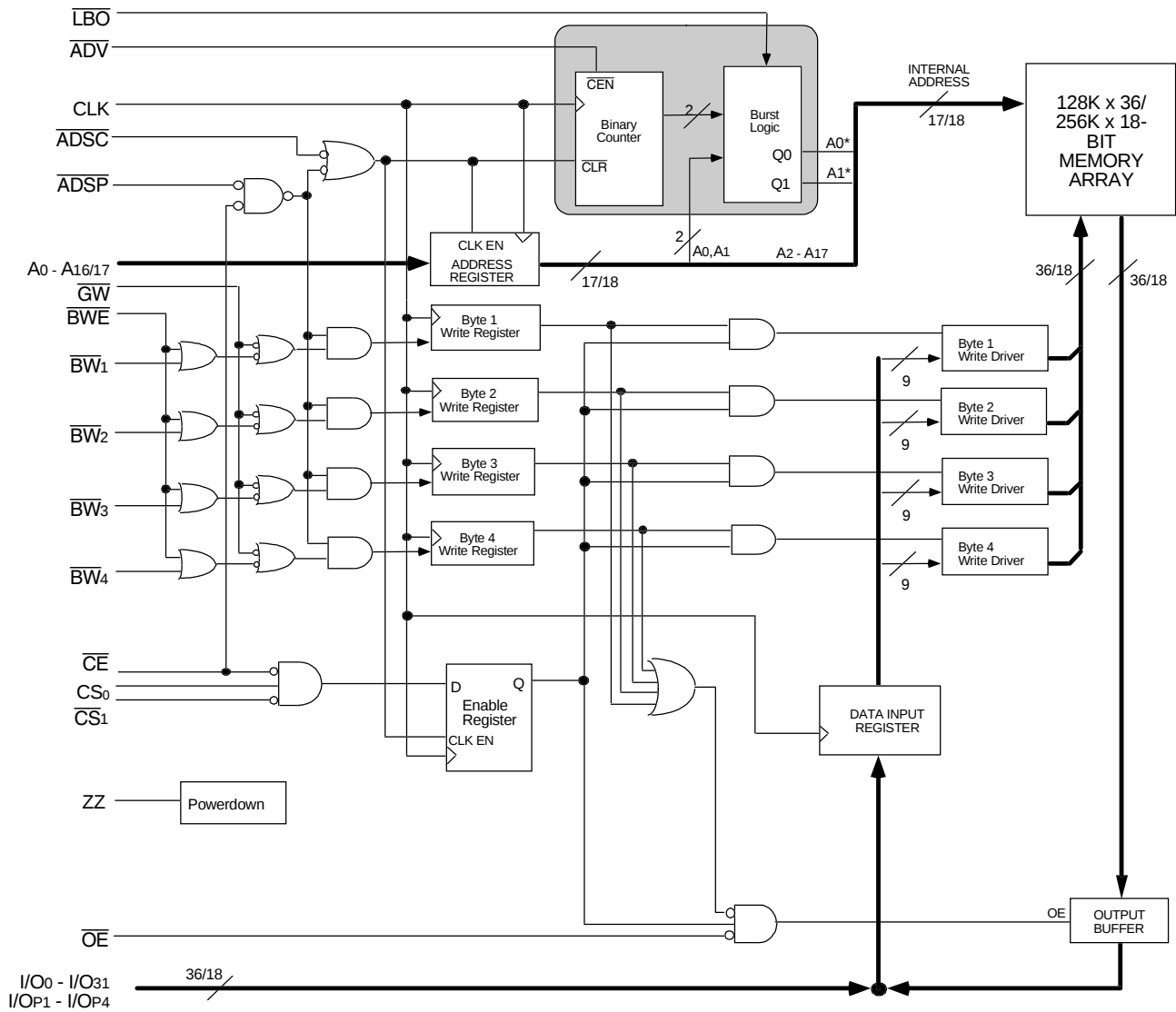
Symbol	Pin Function	I/O	Active	Description
A0-A17	Address Inputs	I	N/A	Synchronous Address inputs. The address register is triggered by a combination of the rising edge of CLK and $\overline{\text{ADSC}}$ Low or $\overline{\text{ADSP}}$ Low and $\overline{\text{CE}}$ Low.
$\overline{\text{ADSC}}$	Address Status (Cache Controller)	I	LOW	Synchronous Address Status from Cache Controller. $\overline{\text{ADSC}}$ is an active LOW input that is used to load the address registers with new addresses.
$\overline{\text{ADSP}}$	Address Status (Processor)	I	LOW	Synchronous Address Status from Processor. $\overline{\text{ADSP}}$ is an active LOW input that is used to load the address registers with new addresses. $\overline{\text{ADSP}}$ is gated by $\overline{\text{CE}}$.
$\overline{\text{ADV}}$	Burst Address Advance	I	LOW	Synchronous Address Advance. $\overline{\text{ADV}}$ is an active LOW input that is used to advance the internal burst counter, controlling burst access after the initial address is loaded. When the input is HIGH the burst counter is not incremented; that is, there is no address advance.
$\overline{\text{BWE}}$	Byte Write Enable	I	LOW	Synchronous byte write enable gates the byte write inputs $\overline{\text{BW1}}\text{--}\overline{\text{BW4}}$. If $\overline{\text{BWE}}$ is LOW at the rising edge of CLK then $\overline{\text{BWx}}$ inputs are passed to the next stage in the circuit. If $\overline{\text{BWE}}$ is HIGH then the byte write inputs are blocked and only $\overline{\text{GW}}$ can initiate a write cycle.
$\overline{\text{BW1}}\text{--}\overline{\text{BW4}}$	Individual Byte Write Enables	I	LOW	Synchronous byte write enables. $\overline{\text{BW1}}$ controls I/O0-7, I/OP1, $\overline{\text{BW2}}$ controls I/O8-15, I/OP2, etc. Any active byte write causes all outputs to be disabled.
$\overline{\text{CE}}$	Chip Enable	I	LOW	Synchronous chip enable. $\overline{\text{CE}}$ is used with CS0 and $\overline{\text{CS1}}$ to enable the IDT71V2577/79. $\overline{\text{CE}}$ also gates $\overline{\text{ADSP}}$.
CLK	Clock	I	N/A	This is the clock input. All timing references for the device are made with respect to this input.
CS0	Chip Select 0	I	HIGH	Synchronous active HIGH chip select. CS0 is used with $\overline{\text{CE}}$ and $\overline{\text{CS1}}$ to enable the chip.
$\overline{\text{CS1}}$	Chip Select 1	I	LOW	Synchronous active LOW chip select. $\overline{\text{CS1}}$ is used with $\overline{\text{CE}}$ and CS0 to enable the chip.
$\overline{\text{GW}}$	Global Write Enable	I	LOW	Synchronous global write enable. This input will write all four 9-bit data bytes when LOW on the rising edge of CLK. $\overline{\text{GW}}$ supersedes individual byte write enables.
I/O0-I/O31 I/OP1-I/OP4	Data Input/Output	I/O	N/A	Synchronous data input/output (I/O) pins. The data input path is registered, triggered by the rising edge of CLK. The data output path is flow-through (no output register).
$\overline{\text{LBO}}$	Linear Burst Order	I	LOW	Asynchronous burst order selection input. When $\overline{\text{LBO}}$ is HIGH, the inter-leaved burst sequence is selected. When $\overline{\text{LBO}}$ is LOW the Linear burst sequence is selected. $\overline{\text{LBO}}$ is a static input and must not change state while the device is operating.
$\overline{\text{OE}}$	Output Enable	I	LOW	Asynchronous output enable. When $\overline{\text{OE}}$ is LOW the data output drivers are enabled on the I/O pins if the chip is also selected. When $\overline{\text{OE}}$ is HIGH the I/O pins are in a high-impedance state.
VDD	Power Supply	N/A	N/A	3.3V core power supply.
VDDQ	Power Supply	N/A	N/A	2.5V I/O Supply.
VSS	Ground	N/A	N/A	Ground.
NC	No Connect	N/A	N/A	NC pins are not electrically connected to the device.
ZZ	Sleep Mode	1	HIGH	Asynchronous sleep mode input. ZZ HIGH will gate the CLK internally and power down the IDT71V2577/79 to its lowest power consumption level. Data retention is guaranteed in Sleep Mode.

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NOTE:

1. All synchronous inputs must meet specified setup and hold times with respect to CLK.

Functional Block Diagram



4877 drw 01

Absolute Maximum Ratings⁽¹⁾

Symbol	Rating	Commercial & Industrial Values	Unit
V _{TERM} ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +4.6	V
V _{TERM} ^(3,6)	Terminal Voltage with Respect to GND	-0.5 to V _{DD}	V
V _{TERM} ^(4,6)	Terminal Voltage with Respect to GND	-0.5 to V _{DD} + 0.5	V
V _{TERM} ^(5,6)	Terminal Voltage with Respect to GND	-0.5 to V _{DDQ} + 0.5	V
T _A ⁽⁷⁾	Commercial Operating Temperature	-0 to +70	°C
	Industrial Operating Temperature	-40 to +85	°C
T _{BIAS}	Temperature Under Bias	-55 to +125	°C
T _{STG}	Storage Temperature	-55 to +125	°C
P _T	Power Dissipation	2.0	W
I _{OUT}	DC Output Current	50	mA

4877 tbl 03

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- V_{DD} terminals only.
- V_{DDQ} terminals only.
- Input terminals only.
- I/O terminals only.
- This is a steady-state DC parameter that applies after the power supplies have ramped up. Power supply sequencing is not necessary; however, the voltage on any input or I/O pin cannot exceed V_{DDQ} during power supply ramp up.
- T_A is the "instant on" case temperature.

Recommended Operating Temperature and Supply Voltage

Grade	Temperature ⁽¹⁾	V _{SS}	V _{DD}	V _{DDQ}
Commercial	0°C to +70°C	0V	3.3V±5%	2.5V±5%
Industrial	-40°C to +85°C	0V	3.3V±5%	2.5V±5%

NOTES:

4877 tbl 04

- T_A is the "instant on" case temperature.

Recommended DC Operating Conditions

Symbol	Parameter	Min.	Typ.	Max.	Unit
V _{DD}	Core Supply Voltage	3.135	3.3	3.465	V
V _{DDQ}	I/O Supply Voltage	2.375	2.5	2.625	V
V _{SS}	Supply Voltage	0	0	0	V
V _{IH}	Input High Voltage - Inputs	1.7	—	V _{DD} + 0.3	V
V _{IH}	Input High Voltage - I/O	1.7	—	V _{DDQ} + 0.3 ⁽¹⁾	V
V _{IL}	Input Low Voltage	-0.3 ⁽²⁾	—	0.7	V

4877 tbl 05

NOTES:

- V_{IH} (max) = V_{DDQ} + 1.0V for pulse width less than t_{CV}/2, once per cycle.
- V_{IL} (min) = -1.0V for pulse width less than t_{CV}/2, once per cycle.

100 Pin TQFP Capacitance

(T_A = +25°C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 3dV	5	pF
C _{I/O}	I/O Capacitance	V _{OUT} = 3dV	7	pF

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165 fBGA Capacitance

(T_A = +25°C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 3dV	TBD	pF
C _{I/O}	I/O Capacitance	V _{OUT} = 3dV	TBD	pF

4877 tbl 07b

NOTE:

- This parameter is guaranteed by device characterization, but not production tested.

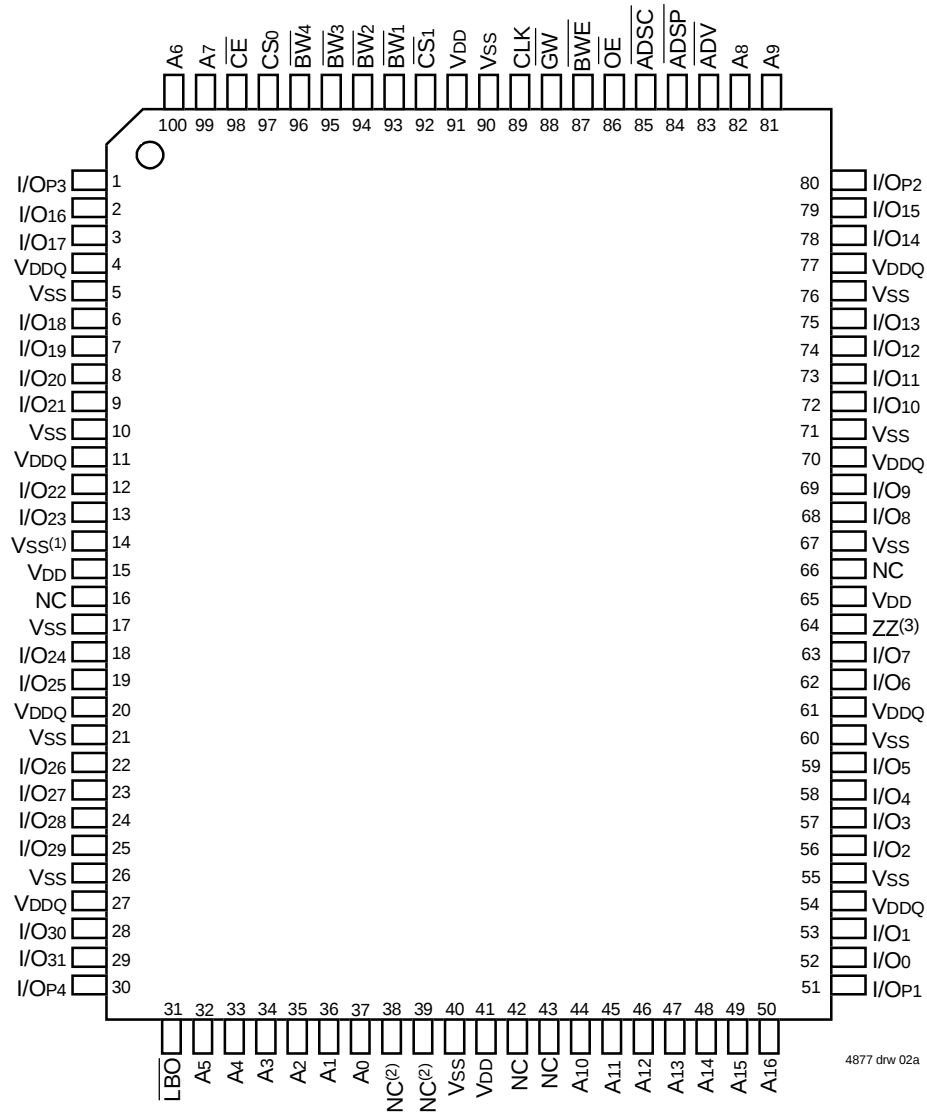
119 BGA Capacitance

(T_A = +25°C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 3dV	7	pF
C _{I/O}	I/O Capacitance	V _{OUT} = 3dV	7	pF

4877 tbl 07a

Pin Configuration – 128K x 36

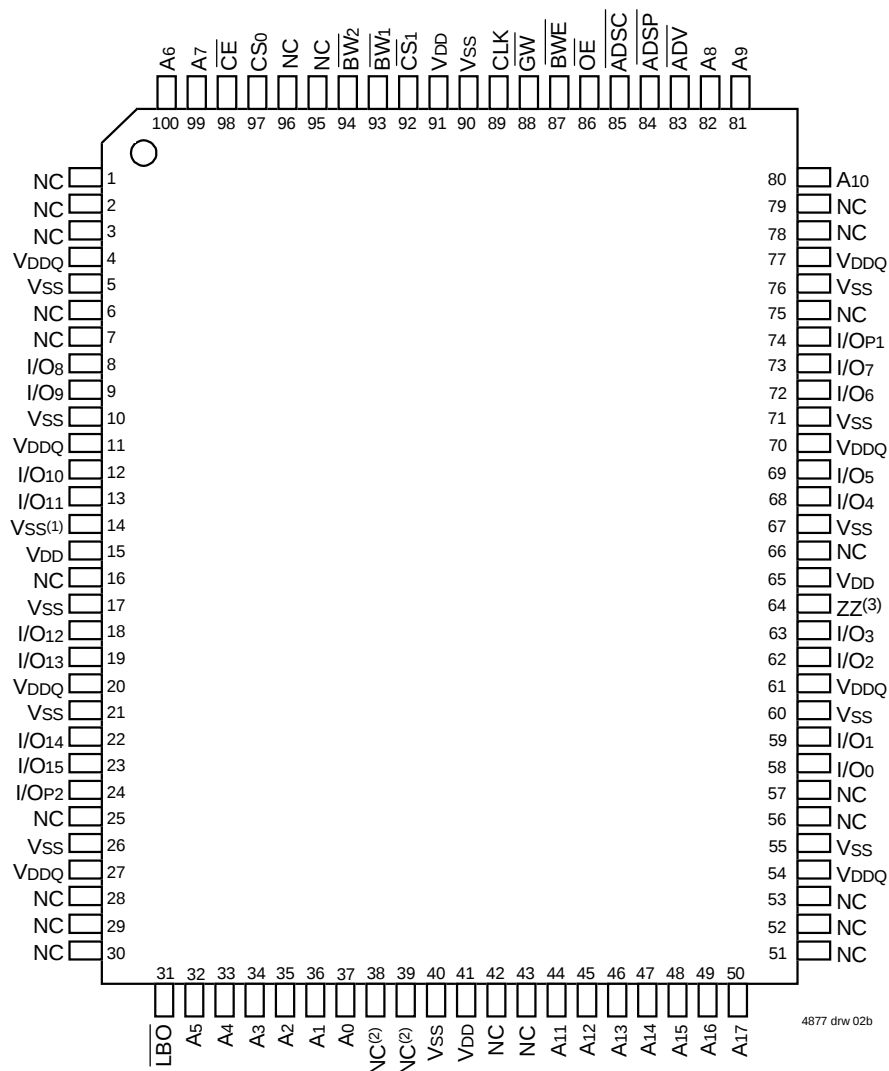


100 TQFP Top View

NOTES:

1. Pin 14 does not have to be directly connected to Vss as long as the input voltage is $\leq V_{IL}$.
2. Pins 38 and 39 can be either NC or connected to Vss.
3. Pin 64 can be left unconnected and the device will always remain in active mode.

Pin Configuration – 256K x 18



100 TQFP Top View

NOTES:

1. Pin 14 does not have to be directly connected to Vss as long as the input voltage is $\leq V_{IL}$.
2. Pins 38 and 39 can be either NC or connected to Vss.
3. Pin 64 can be left unconnected and the device will always remain in active mode.

Pin Configuration – 128K x 36, 119 BGA

	1	2	3	4	5	6	7
A	VDDQ	A6	A4	ADSP	A8	A16	VDDQ
B	NC	CS ₀	A3	ADSC	A9	CS1	NC
C	NC	A7	A2	VDD	A12	A15	NC
D	I/O16	I/OP3	VSS	NC	VSS	I/OP2	I/O15
E	I/O17	I/O18	VSS	CE	VSS	I/O13	I/O14
F	VDDQ	I/O19	VSS	OE	VSS	I/O12	VDDQ
G	I/O20	I/O21	BW3	ADV	BW2	I/O11	I/O10
H	I/O22	I/O23	VSS	GW	VSS	I/O9	I/O8
J	VDDQ	VDD	NC	VDD	NC	VDD	VDDQ
K	I/O24	I/O26	VSS	CLK	VSS	I/O6	I/O7
L	I/O25	I/O27	BW4	NC ⁽²⁾	BW1	I/O4	I/O5
M	VDDQ	I/O28	VSS	BWE	VSS	I/O3	VDDQ
N	I/O29	I/O30	VSS	A1	VSS	I/O2	I/O1
P	I/O31	I/OP4	VSS	A0	VSS	I/O0	I/OP1
R	NC	A5	LBO	VDD	VSS	A13	NC
T	NC	NC	A10	A11	A14	NC	ZZ ⁽³⁾
U	VDDQ	DNU ⁽⁴⁾	DNU ⁽⁴⁾	DNU ^(2,4)	DNU ⁽⁴⁾	DNU ⁽⁴⁾	VDDQ

4877 drw 02c

Top View

Pin Configuration – 256K x 18, 119 BGA

	1	2	3	4	5	6	7
A	VDDQ	A6	A4	ADSP	A8	A16	VDDQ
B	NC	CS ₀	A3	ADSC	A9	CS1	NC
C	NC	A7	A2	VDD	A13	A17	NC
D	I/O8	NC	VSS	NC	VSS	I/O7	NC
E	NC	I/O9	VSS	CE	VSS	NC	I/O6
F	VDDQ	NC	VSS	OE	VSS	I/O5	VDDQ
G	NC	I/O10	BW2	ADV	VSS	NC	I/O4
H	I/O11	NC	VSS	GW	VSS	I/O3	NC
J	VDDQ	VDD	NC	VDD	NC	VDD	VDDQ
K	NC	I/O12	VSS	CLK	VSS	NC	I/O2
L	I/O13	NC	VSS	NC ⁽²⁾	BW1	I/O1	NC
M	VDDQ	I/O14	VSS	BWE	VSS	NC	VDDQ
N	I/O15	NC	VSS	A1	VSS	I/O0	NC
P	NC	I/OP2	VSS	A0	VSS	NC	I/OP1
R	NC	A5	LBO	VDD	VSS	A12	NC
T	NC	A10	A15	NC	A14	A11	ZZ ⁽³⁾
U	VDDQ	DNU ⁽⁴⁾	DNU ⁽⁴⁾	DNU ^(2,4)	DNU ⁽⁴⁾	DNU ⁽⁴⁾	VDDQ

4877 drw 02d

Top View

NOTES:

1. R5 does not have to be directly connected to Vss as long as the input voltage is $\leq V_{IL}$.
2. L4 and U4 can be either NC or connected to Vss.
3. T7 can be left unconnected and the device will always remain in active mode.
4. DNU = Do not use U2, U3, U4, U5 and U6 are reserved for respective JTAG pins: TDI, TDO, TMS, TCK and $\overline{\text{TRST}}$ on future revisions. Within the current version these pins are not connected.

Pin Configuration – 128K x 36, 165 fBGA

	1	2	3	4	5	6	7	8	9	10	11
A	NC ⁽⁴⁾	A7	$\overline{CE}_1$	$\overline{BW}_3$	$\overline{BW}_2$	$\overline{CS}_1$	$\overline{BWE}$	$\overline{ADSC}$	$\overline{ADV}$	A8	NC
B	NC	A6	CS0	$\overline{BW}_4$	$\overline{BW}_1$	CLK	$\overline{GW}$	$\overline{OE}$	$\overline{ADSP}$	A9	NC ⁽⁴⁾
C	I/O _{P3}	NC	V _{DDQ}	V _{SS}	V _{SS}	V _{SS}	V _{SS}	V _{SS}	V _{DDQ}	NC	I/O _{P2}
D	I/O ₁₇	I/O ₁₆	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	I/O ₁₅	I/O ₁₄
E	I/O ₁₉	I/O ₁₈	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	I/O ₁₃	I/O ₁₂
F	I/O ₂₁	I/O ₂₀	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	I/O ₁₁	I/O ₁₀
G	I/O ₂₃	I/O ₂₂	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	I/O ₉	I/O ₈
H	V _{SS} ⁽¹⁾	NC ⁽²⁾	NC	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	NC	NC	ZZ ⁽³⁾
J	I/O ₂₅	I/O ₂₄	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	I/O ₇	I/O ₆
K	I/O ₂₇	I/O ₂₆	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	I/O ₅	I/O ₄
L	I/O ₂₉	I/O ₂₈	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	I/O ₃	I/O ₂
M	I/O ₃₁	I/O ₃₀	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	I/O ₁	I/O ₀
N	I/O _{P4}	NC	V _{DDQ}	V _{SS}	DNU ⁽⁵⁾	NC ⁽⁴⁾	NC ⁽²⁾	V _{SS}	V _{DDQ}	NC	I/O _{P1}
P	NC	NC ⁽⁴⁾	A5	A2	DNU ⁽⁵⁾	A1	DNU ⁽⁵⁾	A10	A13	A14	NC ⁽⁴⁾
R	$\overline{LBO}$	NC ⁽⁴⁾	A4	A3	DNU ⁽⁵⁾	A0	DNU ⁽⁵⁾	A11	A12	A15	A16

4877 tbl 17

Pin Configuration – 256K x 18, 165 fBGA

	1	2	3	4	5	6	7	8	9	10	11
A	NC ⁽⁴⁾	A7	$\overline{CE}$	$\overline{BW}_2$	NC	$\overline{CS}_1$	$\overline{BWE}$	$\overline{ADSC}$	$\overline{ADV}$	A8	A10
B	NC	A6	CS0	NC	$\overline{BW}_1$	CLK	$\overline{GW}$	$\overline{OE}$	$\overline{ADSP}$	A9	NC ⁽⁴⁾
C	NC	NC	V _{DDQ}	V _{SS}	V _{SS}	V _{SS}	V _{SS}	V _{SS}	V _{DDQ}	NC	I/O _{P1}
D	NC	I/O ₈	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	NC	I/O ₇
E	NC	I/O ₉	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	NC	I/O ₆
F	NC	I/O ₁₀	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	NC	I/O ₅
G	NC	I/O ₁₁	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	NC	I/O ₄
H	V _{SS} ⁽¹⁾	NC ⁽²⁾	NC	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	NC	NC	ZZ ⁽³⁾
J	I/O ₁₂	NC	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	I/O ₃	NC
K	I/O ₁₃	NC	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	I/O ₂	NC
L	I/O ₁₄	NC	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	I/O ₁	NC
M	I/O ₁₅	NC	V _{DDQ}	V _{DD}	V _{SS}	V _{SS}	V _{SS}	V _{DD}	V _{DDQ}	I/O ₀	NC
N	I/O _{P2}	NC	V _{DDQ}	V _{SS}	DNU ⁽⁵⁾	NC ⁽⁴⁾	NC ⁽²⁾	V _{SS}	V _{DDQ}	NC	NC
P	NC	NC ⁽⁴⁾	A5	A2	DNU ⁽⁵⁾	A1	DNU ⁽⁵⁾	A11	A14	A15	NC ⁽⁴⁾
R	$\overline{LBO}$	NC ⁽⁴⁾	A4	A3	DNU ⁽⁵⁾	A0	DNU ⁽⁵⁾	A12	A13	A16	A17

4877 tbl 17a

NOTES:

1. H1 does not have to be directly V_{SS} as long as input voltage is $\leq V_{IL}$.
2. H2 and N7 can be either NC or connected to V_{SS}.
3. H11 can be left unconnected and the device will always remain in active mode.
4. Pins P11, N6, B11, A1, R2 and P2 are reserved for 9M, 18M, 36M, 72M, 144M and 288M respectively.
5. DNU = Do not use; Pins P5, P7, R5, R7 and N5 are reserved for respective JTAG pins: TDI, TDO, TMS, TCK and $\overline{TRST}$ on future revisions. Within the current version these pins are not connected.

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range ($V_{DD} = 3.3V \pm 5\%$)

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
$ I_{LI} $	Input Leakage Current	$V_{DD} = \text{Max.}, V_{IN} = 0V \text{ to } V_{DD}$	—	5	μA
$ I_{LI} $	ZZ and $\overline{LBO}$ Input Leakage Current ⁽¹⁾	$V_{DD} = \text{Max.}, V_{IN} = 0V \text{ to } V_{DD}$	—	30	μA
$ I_{LO} $	Output Leakage Current	$V_{OUT} = 0V \text{ to } V_{DDQ}$, Device Deselected	—	5	μA
V_{OL}	Output Low Voltage	$I_{OL} = +6mA$, $V_{DD} = \text{Min.}$	—	0.4	V
V_{OH}	Output High Voltage	$I_{OH} = -6mA$, $V_{DD} = \text{Min.}$	2.0	—	V

4877 tbl 08

NOTE:

1. The $\overline{LBO}$ pin will be internally pulled to V_{DD} if it is not actively driven in the application and the ZZ pin will be internally pulled to V_{SS} if not actively driven.

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range⁽¹⁾

Symbol	Parameter	Test Conditions	7.5ns	8ns		8.5ns		Unit
			Com'l Only	Com'l	Ind	Com'l	Ind	
I_{DD}	Operating Power Supply Current	Device Selected, Outputs Open, $V_{DD} = \text{Max.}$, $V_{DDQ} = \text{Max.}$, $V_{IN} \geq V_{IH}$ or $\leq V_{IL}$, $f = f_{MAX}$ ⁽²⁾	255	200	210	180	190	mA
I_{SB1}	CMOS Standby Power Supply Current	Device Deselected, Outputs Open, $V_{DD} = \text{Max.}$, $V_{DDQ} = \text{Max.}$, $V_{IN} \geq V_{HD}$ or $\leq V_{LD}$, $f = 0$ ^(2,3)	30	30	35	30	35	mA
I_{SB2}	Clock Running Power Supply Current	Device Deselected, Outputs Open, $V_{DD} = \text{Max.}$, $V_{DDQ} = \text{Max.}$, $V_{IN} \geq V_{HD}$ or $\leq V_{LD}$, $f = f_{MAX}$ ^(2,3)	90	85	95	80	90	mA
I_{ZZ}	Full Sleep Mode Supply Current	$ZZ \geq V_{HD}$, $V_{DD} = \text{Max.}$	30	30	35	30	35	mA

4877 tbl 09

NOTES:

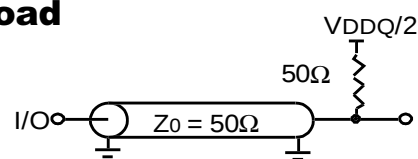
1. All values are maximum guaranteed values.
2. At $f = f_{MAX}$, inputs are cycling at the maximum frequency of read cycles of $1/t_{CYC}$ while $\overline{ADSC} = \text{LOW}$; $f=0$ means no input lines are changing.
3. For I/Os $V_{HD} = V_{DDQ} - 0.2V$, $V_{LD} = 0.2V$. For other inputs $V_{HD} = V_{DD} - 0.2V$, $V_{LD} = 0.2V$.

AC Test Conditions ($V_{DDQ} = 2.5V$)

Input Pulse Levels	0 to 2.5V
Input Rise/Fall Times	2ns
Input Timing Reference Levels	$(V_{DDQ}/2)$
Output Timing Reference Levels	$(V_{DDQ}/2)$
AC Test Load	See Figure 1

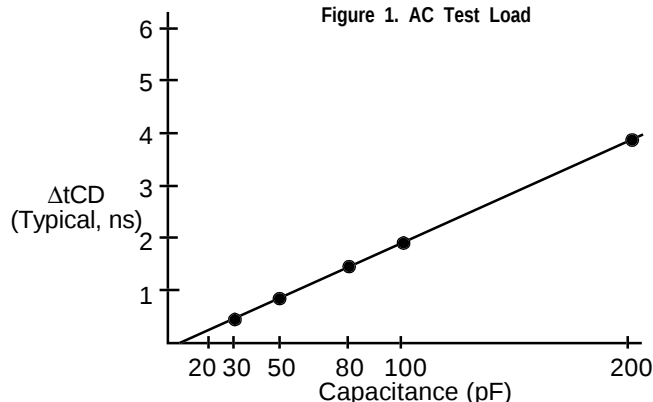
4877 tbl 10

AC Test Load



4877d03

Figure 1. AC Test Load



4877d05

Figure 2. Lumped Capacitive Load, Typical Derating

Synchronous Truth Table^(1,3)

Operation	Address Used	$\overline{CE}$	CS_0	$\overline{CS}_1$	$\overline{ADSP}$	$\overline{ADSC}$	$\overline{ADV}$	$\overline{GW}$	$\overline{BWE}$	$\overline{BW}_x$	$\overline{OE}^{(2)}$	CLK	I/O
Deselected Cycle, Power Down	None	H	X	X	X	L	X	X	X	X	X	↑	HI-Z
Deselected Cycle, Power Down	None	L	X	H	L	X	X	X	X	X	X	↑	HI-Z
Deselected Cycle, Power Down	None	L	L	X	L	X	X	X	X	X	X	↑	HI-Z
Deselected Cycle, Power Down	None	L	X	H	X	L	X	X	X	X	X	↑	HI-Z
Deselected Cycle, Power Down	None	L	L	X	X	L	X	X	X	X	X	↑	HI-Z
Read Cycle, Begin Burst	External	L	H	L	L	X	X	X	X	X	L	↑	DOUT
Read Cycle, Begin Burst	External	L	H	L	L	X	X	X	X	X	H	↑	HI-Z
Read Cycle, Begin Burst	External	L	H	L	H	L	X	H	H	X	L	↑	DOUT
Read Cycle, Begin Burst	External	L	H	L	H	L	X	H	L	H	L	↑	DOUT
Read Cycle, Begin Burst	External	L	H	L	H	L	X	H	L	H	H	↑	HI-Z
Write Cycle, Begin Burst	External	L	H	L	H	L	X	H	L	L	X	↑	DIN
Write Cycle, Begin Burst	External	L	H	L	H	L	X	L	X	X	X	↑	DIN
Read Cycle, Continue Burst	Next	X	X	X	H	H	L	H	H	X	L	↑	DOUT
Read Cycle, Continue Burst	Next	X	X	X	H	H	L	H	H	X	H	↑	HI-Z
Read Cycle, Continue Burst	Next	X	X	X	H	H	L	H	X	H	L	↑	DOUT
Read Cycle, Continue Burst	Next	X	X	X	H	H	L	H	X	H	H	↑	HI-Z
Read Cycle, Continue Burst	Next	H	X	X	X	H	L	H	H	X	L	↑	DOUT
Read Cycle, Continue Burst	Next	H	X	X	X	H	L	H	H	X	H	↑	HI-Z
Read Cycle, Continue Burst	Next	H	X	X	X	H	L	H	X	H	L	↑	DOUT
Read Cycle, Continue Burst	Next	H	X	X	X	H	L	H	X	H	H	↑	HI-Z
Write Cycle, Continue Burst	Next	X	X	X	H	H	L	H	L	L	X	↑	DIN
Write Cycle, Continue Burst	Next	X	X	X	H	H	L	L	X	X	X	↑	DIN
Write Cycle, Continue Burst	Next	H	X	X	X	H	L	H	L	L	X	↑	DIN
Write Cycle, Continue Burst	Next	H	X	X	X	H	L	L	X	X	X	↑	DIN
Read Cycle, Suspend Burst	Current	X	X	X	H	H	H	H	H	X	L	↑	DOUT
Read Cycle, Suspend Burst	Current	X	X	X	H	H	H	H	H	X	H	↑	HI-Z
Read Cycle, Suspend Burst	Current	X	X	X	H	H	H	H	X	H	L	↑	DOUT
Read Cycle, Suspend Burst	Current	X	X	X	H	H	H	H	X	H	H	↑	HI-Z
Read Cycle, Suspend Burst	Current	H	X	X	X	H	H	H	H	X	L	↑	DOUT
Read Cycle, Suspend Burst	Current	H	X	X	X	H	H	H	H	X	H	↑	HI-Z
Read Cycle, Suspend Burst	Current	H	X	X	X	H	H	H	X	H	L	↑	DOUT
Read Cycle, Suspend Burst	Current	H	X	X	X	H	H	H	X	H	H	↑	HI-Z
Write Cycle, Suspend Burst	Current	X	X	X	H	H	H	H	L	L	X	↑	DIN
Write Cycle, Suspend Burst	Current	X	X	X	H	H	H	L	X	X	X	↑	DIN
Write Cycle, Suspend Burst	Current	H	X	X	X	H	H	H	L	L	X	↑	DIN
Write Cycle, Suspend Burst	Current	H	X	X	X	H	H	L	X	X	X	↑	DIN

NOTES:

1. L = V_{IL} , H = V_{IH} , X = Don't Care.
2. $\overline{OE}$ is an asynchronous input.
3. ZZ = low for this table.

4877 tbl 11

Synchronous Write Function Truth Table^(1,2)

Operation	$\overline{GW}$	$\overline{BWE}$	$\overline{BW_1}$	$\overline{BW_2}$	$\overline{BW_3}$	$\overline{BW_4}$
Read	H	H	X	X	X	X
Read	H	L	H	H	H	H
Write all Bytes	L	X	X	X	X	X
Write all Bytes	H	L	L	L	L	L
Write Byte 1 ⁽³⁾	H	L	L	H	H	H
Write Byte 2 ⁽³⁾	H	L	H	L	H	H
Write Byte 3 ⁽³⁾	H	L	H	H	L	H
Write Byte 4 ⁽³⁾	H	L	H	H	H	L

4877 tbl 12

NOTES:

1. L = V_{IL} , H = V_{IH} , X = Don't Care.
2. $\overline{BW_3}$ and $\overline{BW_4}$ are not applicable for the IDT71V2579.
3. Multiple bytes may be selected during the same cycle.

Asynchronous Truth Table⁽¹⁾

Operation ⁽²⁾	$\overline{OE}$	ZZ	I/O Status	Power
Read	L	L	Data Out	Active
Read	H	L	High-Z	Active
Write	X	L	High-Z – Data In	Active
Deselected	X	L	High-Z	Standby
Sleep Mode	X	H	High-Z	Sleep

4877 tbl 13

NOTES:

1. L = V_{IL} , H = V_{IH} , X = Don't Care.
2. Synchronous function pins must be biased appropriately to satisfy operation requirements.

Interleaved Burst Sequence Table ($\overline{LBO}=V_{DD}$)

	Sequence 1		Sequence 2		Sequence 3		Sequence 4	
	A1	A0	A1	A0	A1	A0	A1	A0
First Address	0	0	0	1	1	0	1	1
Second Address	0	1	0	0	1	1	1	0
Third Address	1	0	1	1	0	0	0	1
Fourth Address ⁽¹⁾	1	1	1	0	0	1	0	0

4877 tbl 14

NOTE:

1. Upon completion of the Burst sequence the counter wraps around to its initial state.

Linear Burst Sequence Table ($\overline{LBO}=V_{SS}$)

	Sequence 1		Sequence 2		Sequence 3		Sequence 4	
	A1	A0	A1	A0	A1	A0	A1	A0
First Address	0	0	0	1	1	0	1	1
Second Address	0	1	1	0	1	1	0	0
Third Address	1	0	1	1	0	0	0	1
Fourth Address ⁽¹⁾	1	1	0	0	0	1	1	0

4877 tbl 15

NOTE:

1. Upon completion of the Burst sequence the counter wraps around to its initial state.

AC Electrical Characteristics

(V_{DD} = 3.3V ±5%, Commercial and Industrial Temperature Ranges)

Symbol	Parameter	7.5ns ⁽⁵⁾		8ns		8.5ns		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
Clock Parameter								
t _{CYC}	Clock Cycle Time	8.5	—	10	—	11.5	—	ns
t _{CH} ⁽¹⁾	Clock High Pulse Width	3	—	4	—	4.5	—	ns
t _{CL} ⁽¹⁾	Clock Low Pulse Width	3	—	4	—	4.5	—	ns
Output Parameters								
t _{CD}	Clock High to Valid Data	—	7.5	—	8	—	8.5	ns
t _{ODC}	Clock High to Data Change	2	—	2	—	2	—	ns
t _{OLZ} ⁽²⁾	Clock High to Output Active	0	—	0	—	0	—	ns
t _{CHZ} ⁽²⁾	Clock High to Data High-Z	2	3.5	2	3.5	2	3.5	ns
t _{OE}	Output Enable Access Time	—	3.5	—	3.5	—	3.5	ns
t _{OLZ} ⁽²⁾	Output Enable Low to Output Active	0	—	0	—	0	—	ns
t _{OHZ} ⁽²⁾	Output Enable High to Output High-Z	—	3.5	—	3.5	—	3.5	ns
Set Up Times								
t _{SA}	Address Setup Time	1.5	—	2	—	2	—	ns
t _{SS}	Address Status Setup Time	1.5	—	2	—	2	—	ns
t _{SD}	Data In Setup Time	1.5	—	2	—	2	—	ns
t _{SW}	Write Setup Time	1.5	—	2	—	2	—	ns
t _{SAV}	Address Advance Setup Time	1.5	—	2	—	2	—	ns
t _{SC}	Chip Enable/Select Setup Time	1.5	—	2	—	2	—	ns
Hold Times								
t _{HA}	Address Hold Time	0.5	—	0.5	—	0.5	—	ns
t _{HS}	Address Status Hold Time	0.5	—	0.5	—	0.5	—	ns
t _{HD}	Data In Hold Time	0.5	—	0.5	—	0.5	—	ns
t _{HW}	Write Hold Time	0.5	—	0.5	—	0.5	—	ns
t _{HAV}	Address Advance Hold Time	0.5	—	0.5	—	0.5	—	ns
t _{HC}	Chip Enable/Select Hold Time	0.5	—	0.5	—	0.5	—	ns
Sleep Mode and Configuration Parameters								
t _{ZZPW}	ZZ Pulse Width	100	—	100	—	100	—	ns
t _{ZZR} ⁽³⁾	ZZ Recovery Time	100	—	100	—	100	—	ns
t _{CFG} ⁽⁴⁾	Configuration Set-up Time	34	—	40	—	50	—	ns

4877 tbl 16

NOTES:

1. Measured as HIGH above V_{IH} and LOW below V_{IL}.
2. Transition is measured ±200mV from steady-state.
3. Device must be deselected when powered-up from sleep mode.
4. t_{CFG} is the minimum time required to configure the device based on the $\overline{\text{LB0}}$ input. $\overline{\text{LB0}}$ is a static input and must not change during normal operation.
5. Commercial temperature range only.

Timing Waveform of Flow-Through Read Cycle^(1,2)



NOTES:

1. **O1 (Ay)** represents the first output from the external address **Ax**. **O1 (Ay)** represents the first output from the external address **Ay**; **O2 (Ay)** represents the next output data in the burst sequence of the base address **Ay**, etc. where **A0** and **A1** are advancing for the four word burst in the sequence defined by the state of the **LBO** input.
2. **ZZ** input is **LOW** and **LBO** is Don't Care for this cycle.
3. **CS0** timing transitions are identical but inverted to the **OE** and **CS1** signals. For example, when **OE** and **CS1** are **LOW** on this waveform, **CS0** is **HIGH**.

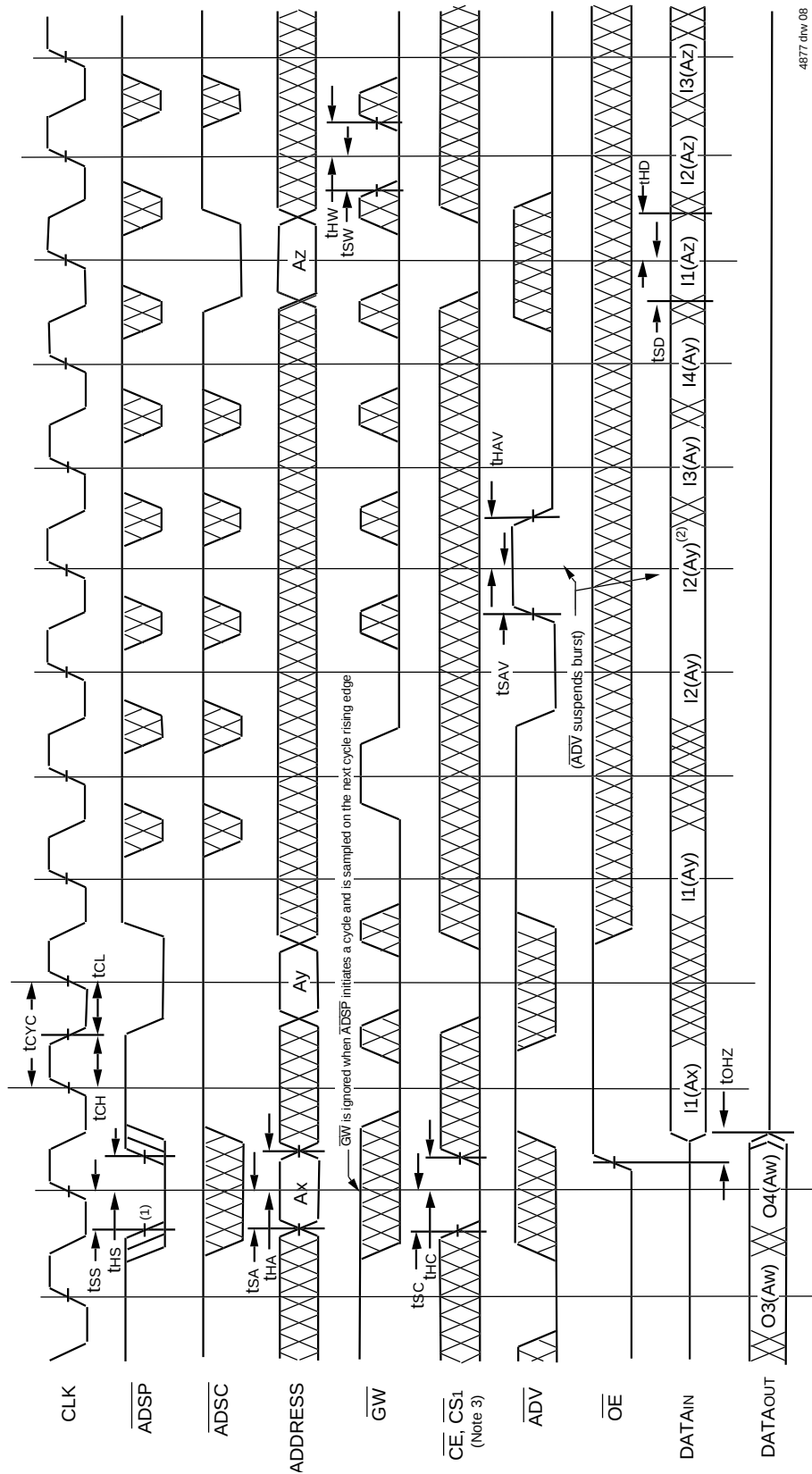
Timing Waveform of Combined Flow-Through Read and Write Cycles^(1,2,3)



1. Device is selected through entire cycle; $\overline{CE}$ and $\overline{CS1}$ are LOW, $CS0$ is HIGH.

1. Device is selected through entire cycle; $\overline{CE}$ and $\overline{CS1}$ are LOW, $CS0$ is HIGH.
2. ZZ input is LOW and $\overline{LBO}$ is Don't Care for this cycle.
3. $O1(Ax)$ represents the first output from the external address Ax . $I1(Ay)$ represents the first input from the external address Ay . $O1(Az)$ represents the first output from the external address Az . $O2(Az)$ represents the next output data in the burst sequence of the base address Az , etc. where $A0$ and $A1$ are advancing for the four word burst in the sequence defined by the state of the $\overline{LBO}$ input.

Timing Waveform of Write Cycle No. 1 - $\overline{GW}$ Controlled^(1,2,3)

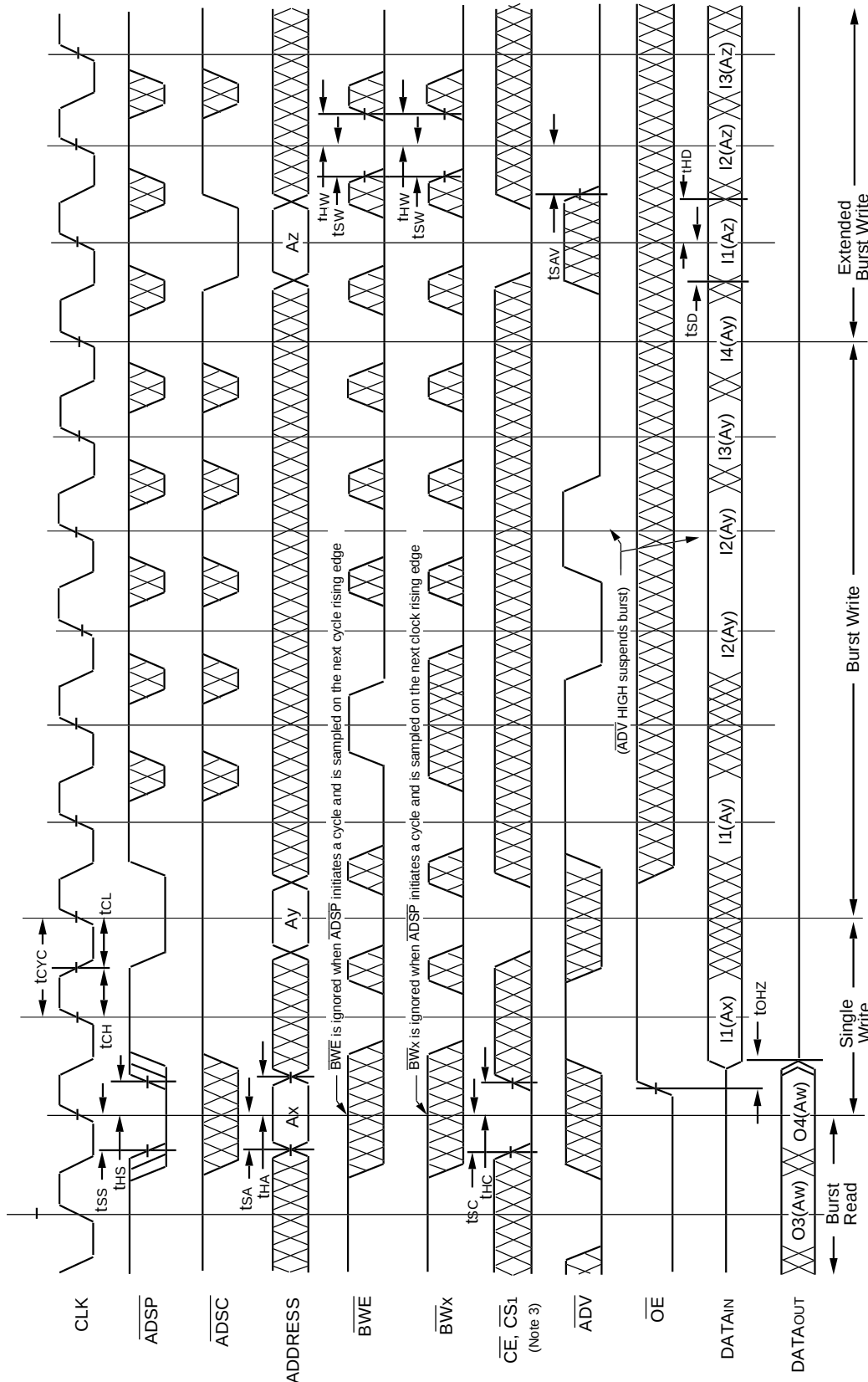


4877 dhw 08

NOTES:

1. ZZ input is LOW, $\overline{BWE}$ is HIGH and $\overline{LBO}$ is Don't Care for this cycle.
2. O4(Aw) represents the final output data in the burst sequence of the base address Aw. I1(Ax) represents the first input from the external address Ay; I2(Ay) represents the next input data in the burst sequence of the base address Ay, etc. where A0 and A1 are advancing for the four word burst in the sequence defined by the state of the LBO input. In the case of input I2(Ay) this data is valid for two cycles because ADV is high and has suspended the burst.
3. CS0 timing transitions are identical but inverted to the $\overline{CE}$ and $\overline{CS1}$ signals. For example, when $\overline{CE}$ and $\overline{CS1}$ are LOW on this waveform, CS0 is HIGH.

Timing Waveform of Write Cycle No. 2 - Byte Controlled^(1,2,3)

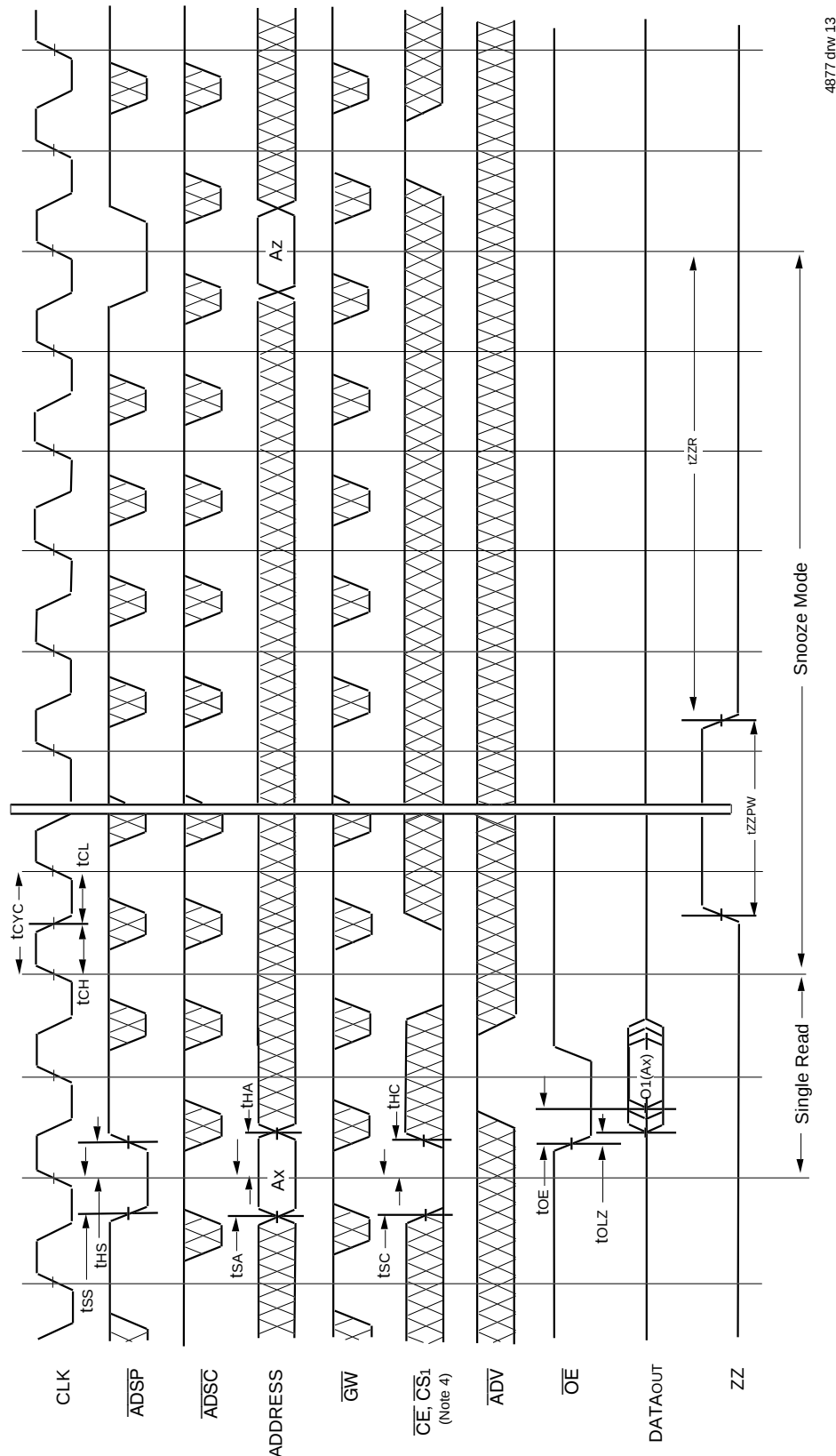


4877 dw 09

NOTES:

1. Z_Z input is LOW, $\overline{GW}$ is HIGH and $\overline{LBO}$ is Don't Care for this cycle.
2. O4(Aw) represents the final output data in the burst sequence of the base address Aw. 11(Ax) represents the first input from the external address Ay; 12(Ay) represents the next input data in the burst sequence of the base address Ay, etc. where A0 and A1 are advancing for the four word burst in the sequence defined by the state of the $\overline{LBO}$ input. In the case of input 12(Ay) this data is valid for two cycles because ADV is high and has suspended the burst.
3. CS0 timing transitions are identical but inverted to the $\overline{CE}$ and $\overline{CS1}$ signals. For example, when $\overline{CE}$ and $\overline{CS1}$ are LOW on this waveform, CS0 is HIGH.

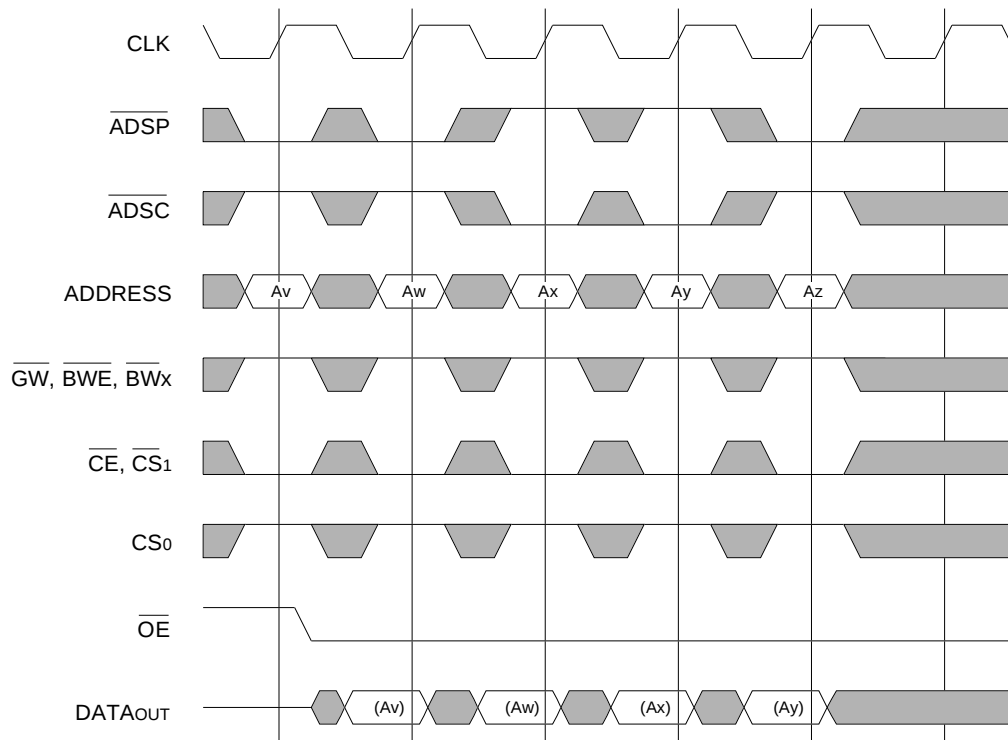
Timing Waveform of Sleep (ZZ) and Power-Down Modes^(1,2,3)



NOTES:

1. Device must power up in deselected Mode
2. $\overline{\text{LBO}}$ is Don't Care for this cycle.
3. It is not necessary to retain the state of the input registers throughout the Power-down cycle.
4. CS timing transitions are identical but inverted to the $\overline{\text{CE}}$ and $\overline{\text{CS1}}$ signals. For example, when $\overline{\text{CE}}$ and $\overline{\text{CS1}}$ are LOW on this waveform, $\overline{\text{CS0}}$ is HIGH.

Non-Burst Read Cycle Timing Waveform

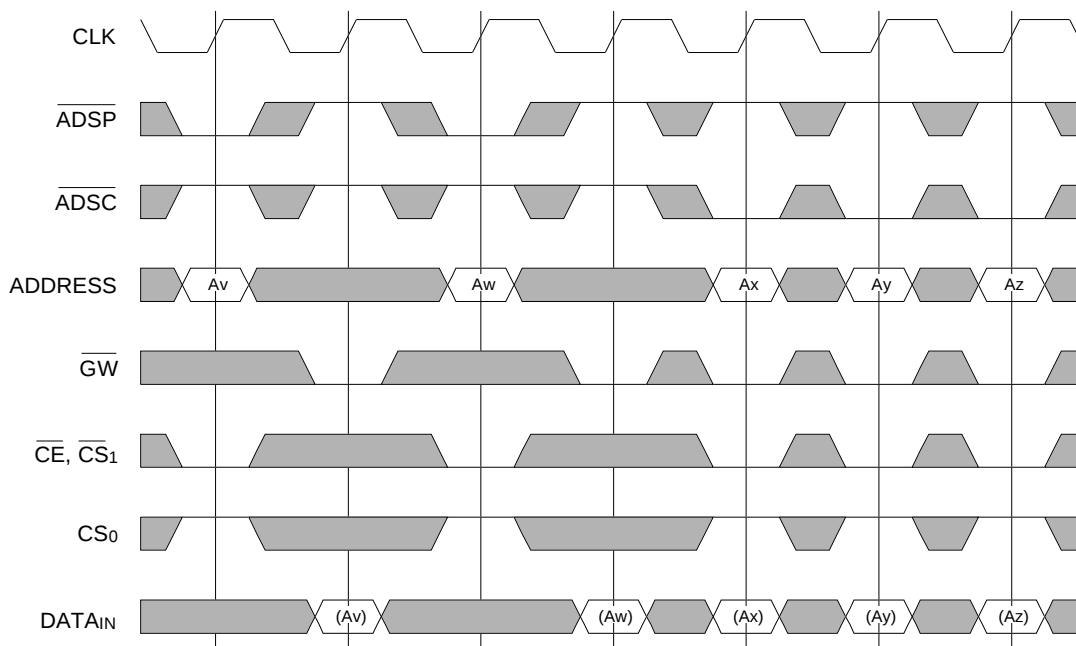


4877 drw 10

NOTES:

1. ZZ input is LOW, $\overline{ADV}$ is HIGH and $\overline{LBO}$ is Don't Care for this cycle.
2. (Ax) represents the data for address Ax, etc.
3. For read cycles, $\overline{ADSP}$ and $\overline{ADSC}$ function identically and are therefore interchangeable.

Non-Burst Write Cycle Timing Waveform

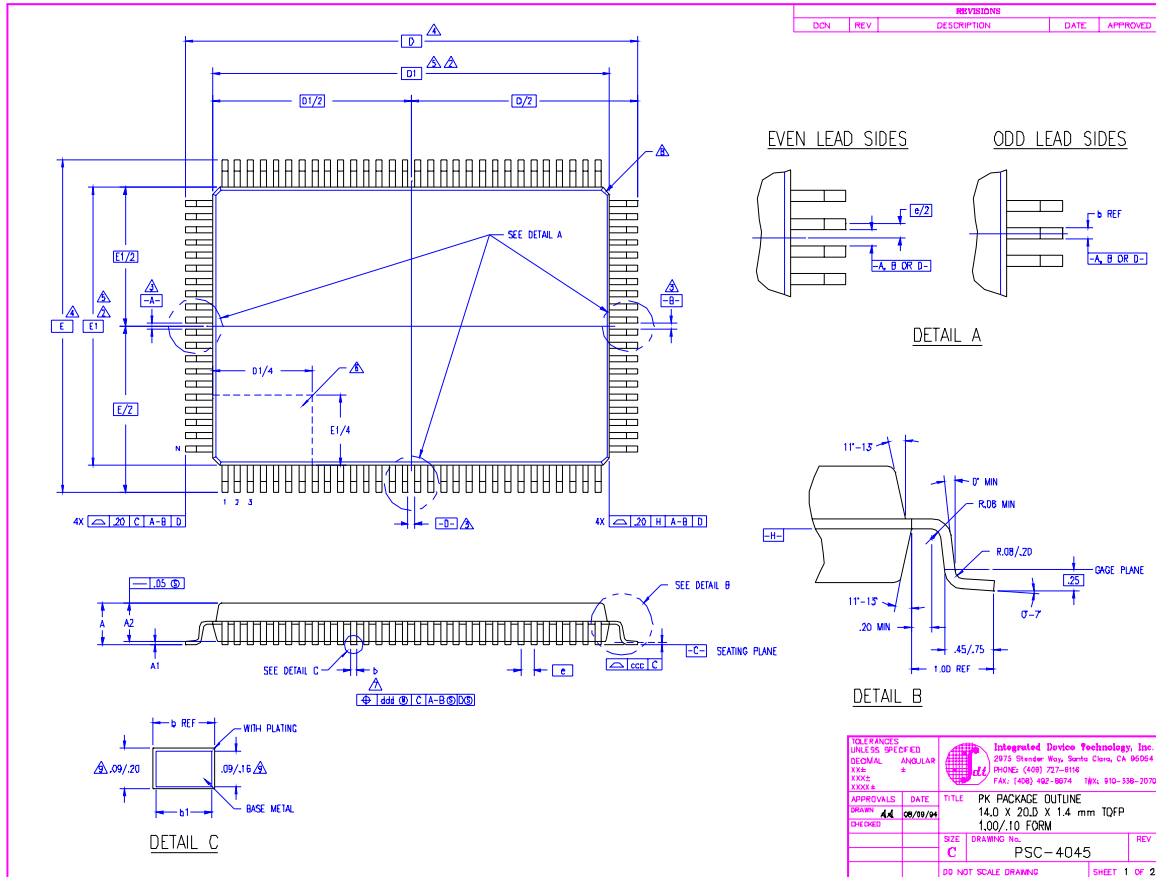


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NOTES:

1. ZZ input is LOW, $\overline{ADV}$ and $\overline{OE}$ are HIGH, and $\overline{LBO}$ is Don't Care for this cycle.
2. (Ax) represents the data for address Ax, etc.
3. Although only $\overline{GW}$ writes are shown, the functionality of $\overline{BWE}$ and $\overline{BWx}$ together is the same as $\overline{GW}$.
4. For write cycles, $\overline{ADSP}$ and $\overline{ADSC}$ have different limitations.

100-Pin Thin Quad Plastic Flatpack (TQFP) Package Diagram Outline

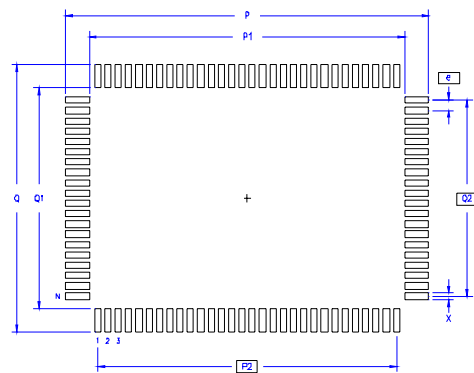


SYMBOL	JEDEC VARIATION			NOTES
	MIN	NOM	MAX	
A	-	-	1.60	
A1	.05	.10	.15	
A2	1.35	1.40	1.45	
D	22.00 BSC			4
D1	20.00 BSC			5.2
E	16.00 BSC			4
E1	14.00 BSC			5.2
N	100			
ND	30			
NE	20			
e	.65 BSC			
b	.22	.32	.38	7
b1	.22	.30	.33	
cct	-	-	.10	
ddd	-	-	.13	

NOTES:

- ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- TOP PACKAGE MAY BE SMALLER THAN BOTTOM PACKAGE BY .15 mm
- DATUMS [A-B] AND [D-] TO BE DETERMINED AT DATUM PLANE [H-]
- DIMENSIONS D AND E ARE TO BE DETERMINED AT SEATING PLANE [C-]
- DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION, ALLOWABLE MOLD PROTRUSION IS .25 mm PER SIDE. D1 AND E1 ARE MAXIMUM BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH
- DETAILS OF PIN 1 IDENTIFIER IS OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED
- DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION, ALLOWABLE DAMBAR PROTRUSION IS .08 mm IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.
- EXACT SHAPE OF EACH CORNER IS OPTIONAL
- THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP
- ALL DIMENSIONS ARE IN MILLIMETERS
- THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-136, VARIATION DJ AND BX

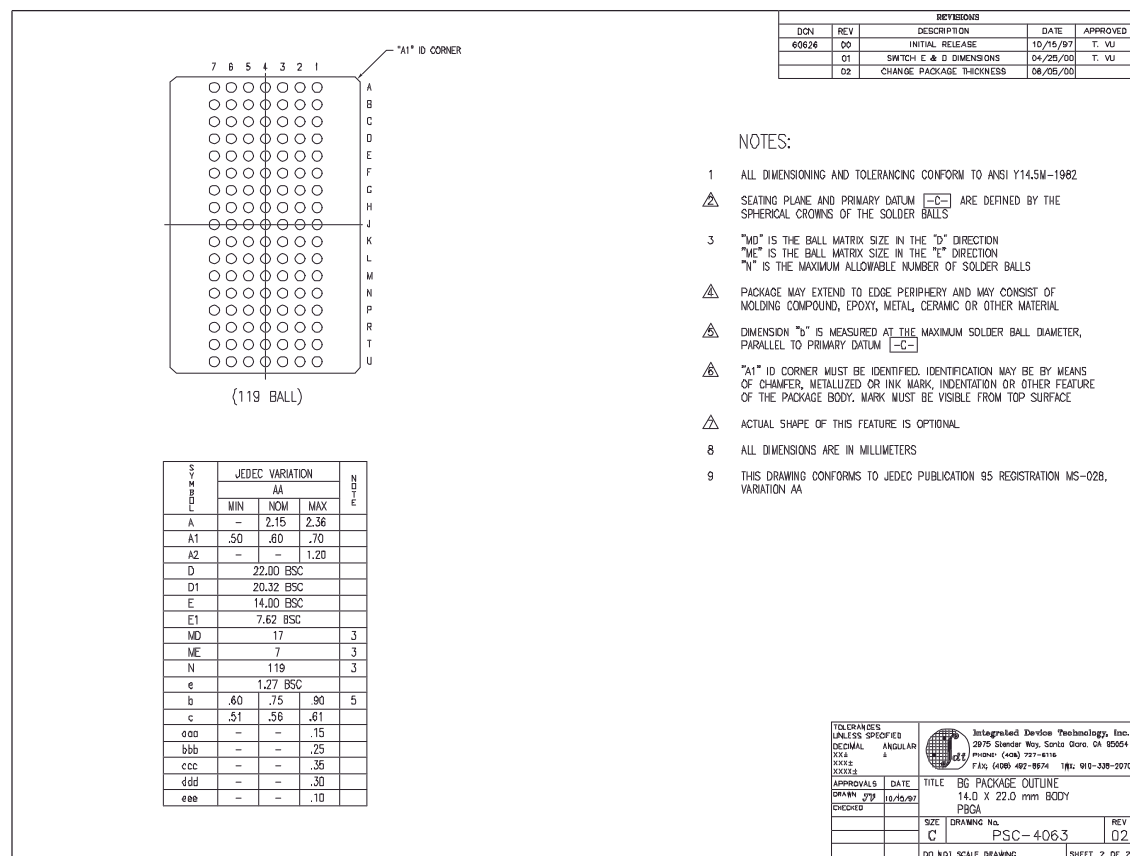
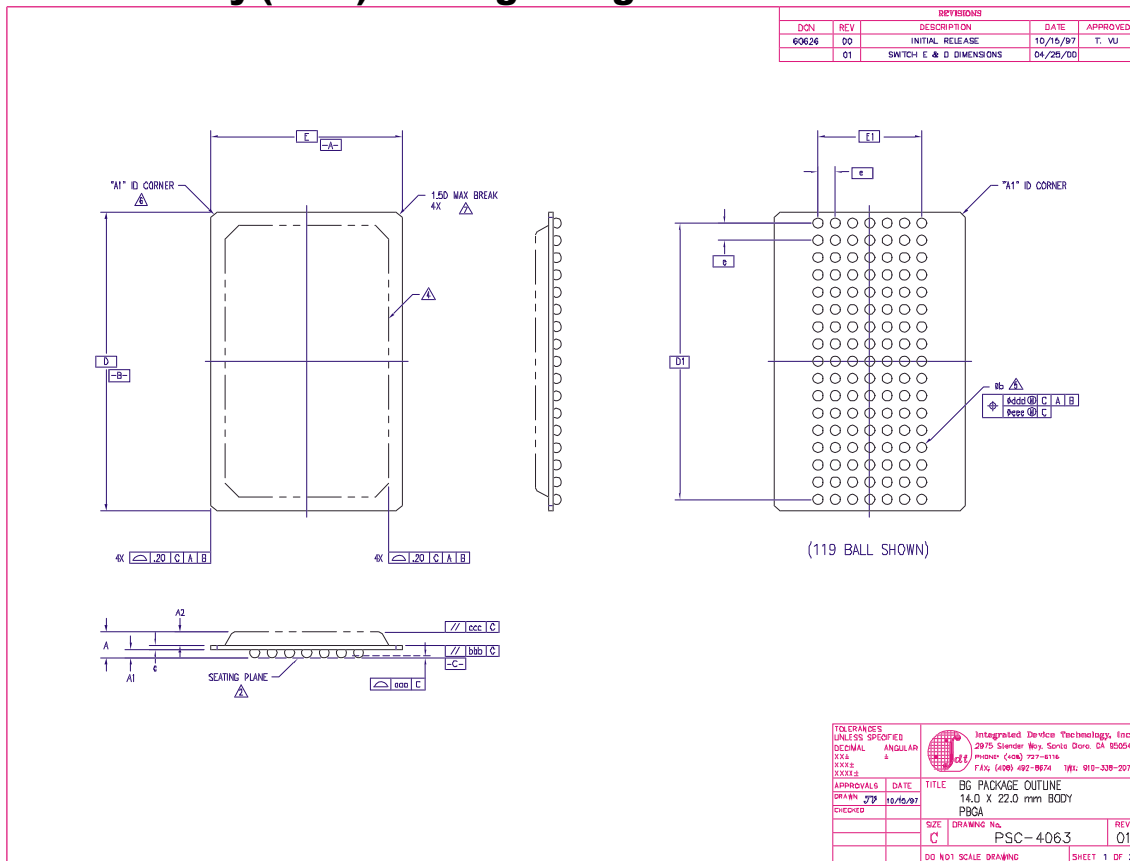
LAND PATTERN DIMENSIONS



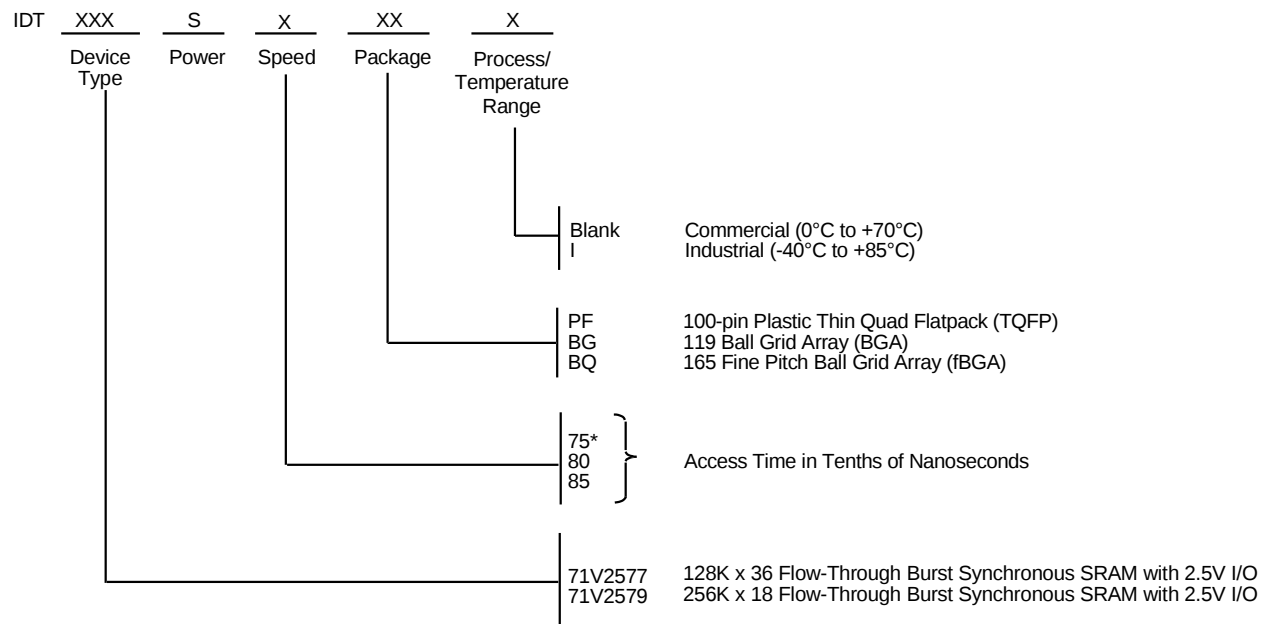
	MIN	MAX
P	22.80	23.00
P1	19.80	20.00
P2	18.85	BSC
Q	16.80	17.00
Q1	13.80	14.00
Q2	12.35	BSC
X	.30	.50
e	.65 BSC	
N	100	

TOLERANCES				
UNLESS SPECIFIED				
DIMENSIONAL	DECIMAL	ANGULAR		
XXX				
XXX				
XXX				
APPROVALS	DATE	TITLE		
DRAWN: 24	08/09/94	PK PACKAGE OUTLINE		
CHECKED:		14.0 x 20.0 x 1.4 mm TQFP		
		1.00/10 FORM		
		SIZE: DRAWING NO.	REV	
		C	PSC-4045	2
DO NOT SCALE DRAWING SHEET 2 OF 2				

119 Ball Grid Array (BGA) Package Diagram Outline



Ordering Information



*Commercial temperature range only.

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Datasheet Document History

7/23/99		Updated to new format
9/17/99	Pg. 2	Revised I/O pin description
	Pg. 3	Revised block diagram for flow-through functionality
	Pg. 8	Revised I _{SB1} and I _{ZZ} for speeds 7.5 to 8.5ns
	Pg. 18	Added 119-lead BGA package diagram
	Pg. 20	Added Datasheet Document History
12/31/99	Pg. 1, 4, 8, 11, 19	Added Industrial Temperature range offerings
04/04/00	Pg. 18	Add 100pin TQFP Package Diagram Outline
	Pg. 4	Add capacitance table for BGA package; Add Industrial temperature to table; insert note to Absolute Max Rating table and Recommended Operating Temperature tables.
06/01/00		Add new package offering, 13 x 15mm 165 fBGA
	Pg. 20	Correct 119BGA Package Diagram Outline
07/15/00	Pg. 7	Add note reference to BG119 pinout
	Pg. 8	Add DNU reference note to BQ165 pinout
	Pg. 20	Update BG119 Package Diagram Outline Dimensions
10/25/00		Remove Preliminary status
	Pg. 8	Add reference note to pin N5 on BQ165 pinout, reserved for JTAG $\overline{\text{TRST}}$



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